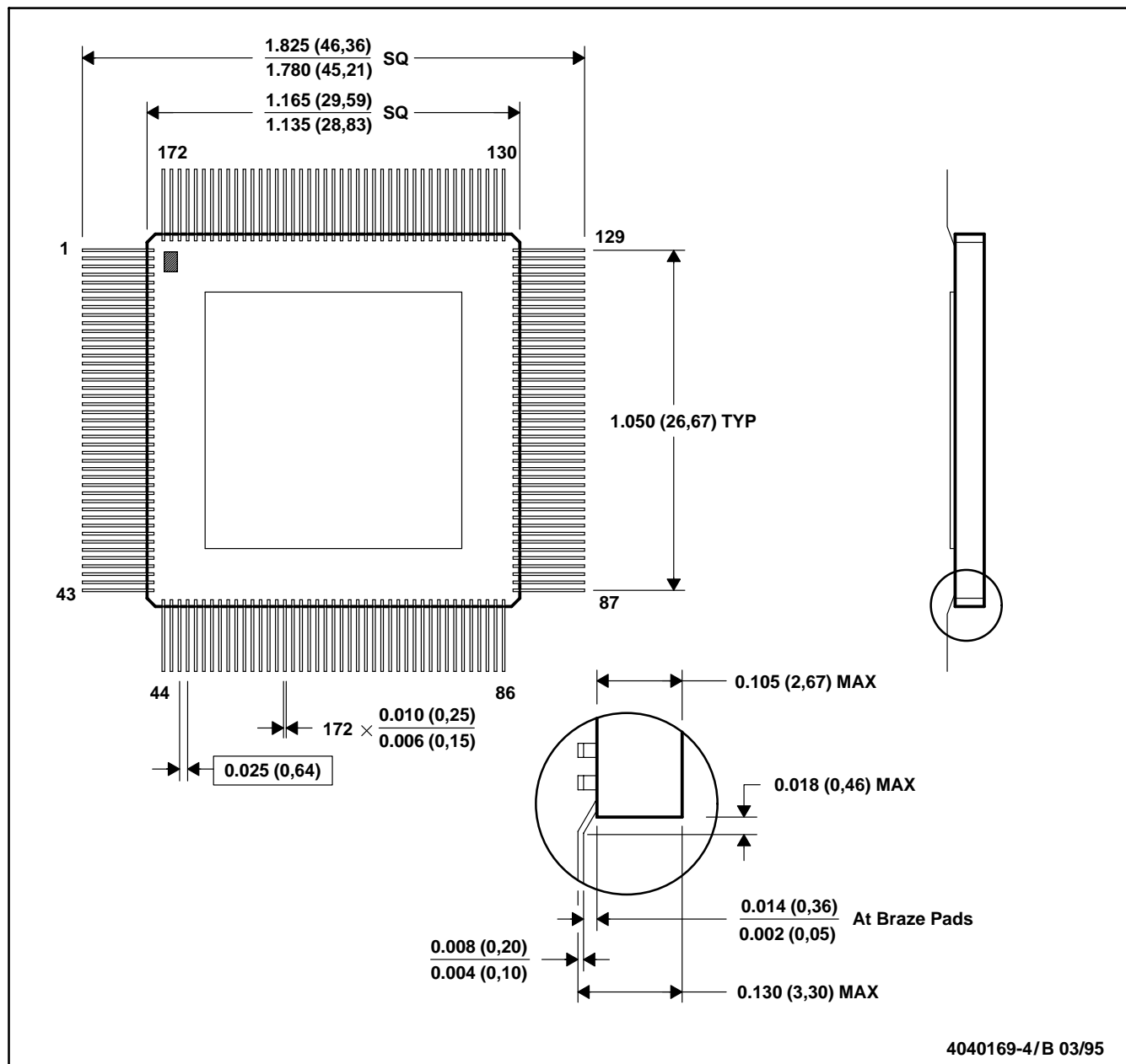


HT (S-CQFP-F172)

CERAMIC QUAD FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a metal lid.
 - The terminals are gold plated.
 - Falls within JEDEC MO-090 AD

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